SCBS027A - FEBRUARY 1989 - REVISED JANUARY 1994

| State-of-the-Art BiCMOS Design Significantly Reduces I_{CCZ} | | PACKAGE VIEW) |
|---|--------------------|--------------------|
| 3-State Outputs Drive Bus Lines or Buffer-Memory Address Registers | 1 <u>OE</u> [1 | 20 V _{CC} |
| P-N-P Inputs Reduce DC Loading | 1A1 [2 2Y4 [3 | 19 20E 18 1Y1 |
| High-Impedance State During Power Up and Power Down | 1A2 4 2Y3 5 | 17 2A4 16 11Y2 |
| Package Options Include Plastic | 1A3 🛮 6 | 15 2A3 |
| Small-Outline (DW) Packages and Standard | 2Y2 🛚 7 | 14 🛮 1Y3 |
| Plastic 300-mil DIPs (N) | 1A4 🛮 8 | 13 🛮 2A2 |
| | 2Y1 🛛 9 | 12 🛮 1Y4 |
| escription | GND [10 | 11 2A1 |
| | | |

This octal buffer and line driver is designed specifically to improve both the performance and

description

density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters. Taken together with the SN64BCT240 and SN64BCT241, these devices provide the choice of selected combinations of inverting and noninverting outputs, symmetrical active-low output-enable (OE) inputs, and complementary OE and \overline{OE} inputs.

The SN64BCT244 is organized as two 4-bit buffers/line drivers with separate output-enable (\overline{OE}) inputs. When \overline{OE} is low, the device passes data from the A inputs to the Y outputs. When \overline{OE} is high, the outputs are in the high-impedance state.

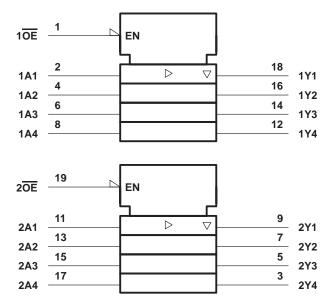
The outputs are in a high-impedance state during power up and power down while the supply voltage is less than approximately 3 V.

The SN64BCT244 is characterized for operation from -40°C to 85°C.

FUNCTION TABLE (each buffer)

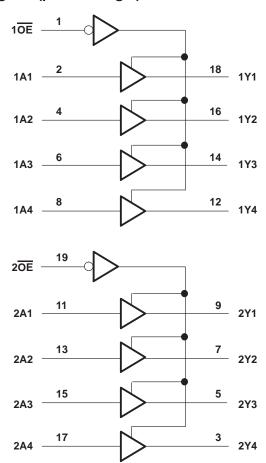
| INPU | JTS | OUTPUT |
|------|-----|--------|
| OE | Α | Y |
| L | Н | Н |
| L | L | L |
| Н | Χ | Z |

logic symbol†



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

| Supply voltage range, V _{CC} | 0.5 V to 7 V |
|--|-----------------------------------|
| Input voltage range, V _I (see Note 1) | –0.5 V to 7 V |
| Voltage range applied to any output in the disabled or power-off state, V _O | $-0.5\ V$ to 5.5 V |
| Voltage range applied to any output in the high state, VO | \dots -0.5 V to V _{CC} |
| Current into any output in the low state, IO | 128 mA |
| Operating free-air temperature range | 40°C to 85°C |
| Storage temperature range | 65°C to 150°C |

[‡] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The input negative voltage rating may be exceeded if the input clamp current rating is observed.



recommended operating conditions

| | | MIN | NOM | MAX | UNIT |
|----------|--------------------------------|-----|-----|-----|------|
| Vcc | Supply voltage | 4.5 | 5 | 5.5 | V |
| VIH | High-level input voltage | 2 | | | V |
| V_{IL} | Low-level input voltage | | | 8.0 | V |
| lik | Input clamp current | | | -18 | mA |
| loh | High-level output current | | | -15 | mA |
| IOL | Low-level output current | | | 64 | mA |
| TA | Operating free-air temperature | -40 | | 85 | °C |

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

| PARAMETER | TEST | CONDITIONS | | MIN | TYP [†] | MAX | UNIT |
|-----------------|--|--|-------------|------|------------------|------|------|
| V _{IK} | $V_{CC} = 4.5 V,$ | $I_{I} = -18 \text{ mA}$ | | | | -1.2 | V |
| ., | V 45V | $I_{OH} = -3 \text{ mA}$ | | 2.4 | 3.3 | | V |
| VOH | V _{CC} = 4.5 V | $I_{OH} = -15 \text{ mA}$ | | 2 | 3.1 | | V |
| V _{OL} | $V_{CC} = 4.5 V,$ | $I_{OL} = 64 \text{ mA}$ | | | 0.42 | 0.55 | V |
| lį | V _{CC} = 5.5 V, | V _I = 7 V | | | | 0.1 | mA |
| lΗ | V _{CC} = 5.5 V, | V _I = 2.7 V | | | | 20 | μΑ |
| IĮL | V _{CC} = 5.5 V, | V _I = 0.5 V | | | | -1 | mA |
| 1 | V _{CC} = 0 to 2.3 V (power up) | $V_0 = 2.7 \text{ V or } 0.5 \text{ V},$ | OE at 0.8 V | | | ± 50 | ^ |
| loz | $V_{CC} = 1.8 \text{ V to 0 (power down)}$ | | OE at 0.6 V | | | ± 50 | μΑ |
| lozh | V _{CC} = 5.5 V, | $V_0 = 2.7 \text{ V}$ | | | | 50 | μΑ |
| lozL | V _{CC} = 5.5 V, | V _O = 0.5 V | | | | -50 | μΑ |
| los† | V _{CC} = 5.5 V, | V _O = 0 | | -100 | | -225 | mA |
| ICCH | $V_{CC} = 5.5 V,$ | Output open | | | 23 | 40 | mA |
| ICCL | $V_{CC} = 5.5 V,$ | Output open | | | 53 | 80 | mA |
| ICCZ | $V_{CC} = 5.5 V,$ | Output open | | | 4 | 10 | mA |

 $[\]overline{\dagger}$ All typical values are at $V_{CC} = 5 \text{ V}$.

switching characteristics (see Note 2)

| PARAMETER | FROM (INPUT) | TO (OUTPUT) | C _L R1 R2 | C = 5 V, = 50 pF = 500 Ω = 500 Ω = 25°C | , | V _{CC} = 4.5 C _L = 50 pl R1 = 500 Q R2 = 500 Q T _A = MIN 1 | 2, 2, | UNIT |
|------------------|-----------------|----------------|----------------------------|---|-----|---|----------|------|
| | | | MIN | TYP | MAX | MIN | MAX | |
| ^t PLH | ^ | V | 1.2 | 2.5 | 4.4 | 0.9 | 5.3 | |
| ^t PHL | A | Y | 1.7 | 3.2 | 5 | 1.4 | 6 | ns |
| ^t PZH | ŌĒ | V | 2 | 5.7 | 7.8 | 2 | 9 | |
| t _{PZL} | OE . | Y | 2 | 5.9 | 8.1 | 2 | 9.4 | ns |
| ^t PHZ | ŌĒ | Y | 2 | 5.4 | 6.7 | 2 | 8 | 200 |
| t _{PLZ} | UE UE | ſ | 2 | 6.1 | 7.6 | 2 | 9.8 | ns |

[§] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions. NOTE 2: Load circuits and voltage waveforms are shown in Section 1.



[‡] Not more than one output should be tested at a time, and the duration of the test should not exceed one second.



PACKAGE OPTION ADDENDUM

6-Feb-2020

PACKAGING INFORMATION

| Orderable Device | Status | Package Type | Package Drawing | Pins | Package Qty | Eco Plan | Lead/Ball Finish | MSL Peak Temp | Op Temp (°C) | Device Marking | Samples |
|------------------|--------|--------------|--------------------|------|----------------|----------------------------|------------------|--------------------|--------------|----------------|---------|
| SN64BCT244DW | ACTIVE | SOIC | DW | 20 | 25 | Green (RoHS & no Sb/Br) | NIPDAU | Level-1-260C-UNLIM | -40 to 85 | 6BCT244 | Samples |
| SN64BCT244NSR | ACTIVE | SO | NS | 20 | 2000 | Green (RoHS & no Sb/Br) | NIPDAU | Level-1-260C-UNLIM | -40 to 85 | DCT244 | Samples |

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead/Ball Finish Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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6-Feb-2020

PACKAGE MATERIALS INFORMATION

www.ti.com 6-May-2017

TAPE AND REEL INFORMATION





| | Dimension designed to accommodate the component width |
|----|---|
| | Dimension designed to accommodate the component length |
| K0 | Dimension designed to accommodate the component thickness |
| W | Overall width of the carrier tape |
| P1 | Pitch between successive cavity centers |

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

| Device | Package Type | Package Drawing | | | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|---------------|-----------------|--------------------|----|------|--------------------------|--------------------------|------------|------------|------------|------------|-----------|------------------|
| SN64BCT244NSR | SO | NS | 20 | 2000 | 330.0 | 24.4 | 8.4 | 13.0 | 2.5 | 12.0 | 24.0 | Q1 |

PACKAGE MATERIALS INFORMATION

www.ti.com 6-May-2017



*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) | |
|---------------|--------------|-----------------|------|------|-------------|------------|-------------|--|
| SN64BCT244NSR | SO | NS | 20 | 2000 | 367.0 | 367.0 | 45.0 | |

MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.





SOIC



NOTES:

- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
- 5. Reference JEDEC registration MS-013.



SOIC



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOIC



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



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